



## **RGTCM Series – 0806(3025)- RoHS Compliance**

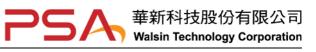
## THIN FILM COMMON MODE FILTER

## **Halogens Free Product**

# P/N: RGTCM0806900H0T

\*Contents in this sheet are subject to change without prior notice.

#### **Approval Sheet**



#### FEATURES

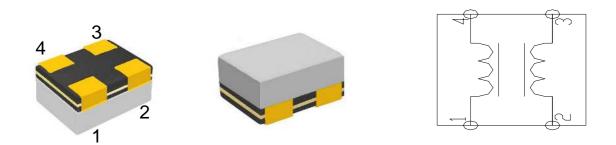
- 1. Miniature footprint: 0.8 X 0.6 X 0.5 mm<sup>3</sup>.
- 2. Thin Film Technology.
- 3. Reflow Solderable SMD Devices.
- 4. Wide Pass Band( Cut- Off Frequency: -3dB : 4 GHz Typical).
- 5. High attenuation for common mode noise.
- 6. This product contains no lead and supports lead-free Ni/Au soldering

#### APPLICATIONS

- 1. For Super Speed Signal Line Application
- 2. LVDS/IEEE1394/HDMI/DVI/MIPI/USB3.0

#### CONSTRUCTION

#### EQUIVALENT CIRCUIT

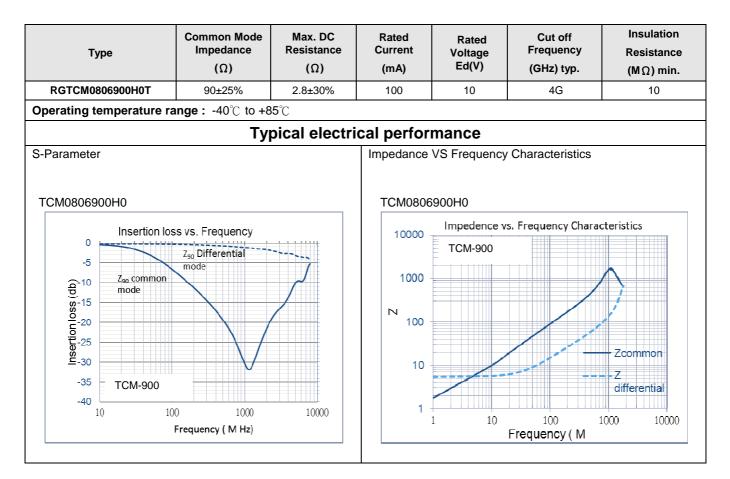


#### DIMENSIONS

Figure	Symbol	Dimension (mm)
	L	$0.88 \pm 0.05$
	W	0.68 ± 0.05
	Т	0.50 ± 0.05
	A	0.15 ± 0.05
	В	0.20 ± 0.05
	С	0.27 ± 0.10
	D	0.62 ± 0.05
	E	0.50 ± 0.10
	F	0.82 ± 0.05



#### **ELECTRICAL CHARACTERISTICS**



#### SOLDER LAND PATTERN

Figure	Symbol	Dimension( mm)
B	A	0.90 ± 0.10
C A	В	0.50 ± 0.10
	С	0.30 ± 0.10
<b>∢_</b> ▶	D	0.30± 0.10

### **Approval Sheet**



#### **RELIABILITY TEST**

Test item	Test condition / Test method	Specification		
Solderability JIS C 0050-4.6 JESD22-B102D Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	<ul> <li>*Solder bath temperature : 235 ± 5°C</li> <li>*Immersion time : 2 ± 0.5 sec</li> <li>*Solder : Sn3Ag0.5Cu for lead-free</li> <li>*Solder bath temperature : 260 ± 5°C</li> <li>*Leaching immersion time : 30 ± 0.5 sec</li> <li>*Solder : SN63A</li> </ul>	At least 95% of a surface of each terminal electrode must be covered by fresh solder. Loss of metallization on the edges of each electrode shall not exceed 25%.		
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec	Loss of metallization on the edges of each electrode shall not exceed 25%. No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.		
	*Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	Table 1       Appearance     No damaged       Common Mode     Within ± 20%		
Drop Test	*!   sight : 75 see	Impedance Change       DC Resistance       Change		
Vibration JIS C 0040	<ul> <li>*Height : 75 cm</li> <li>*Test Surface : Rigid surface of concrete or steel.</li> <li>*Times : 6 surfaces for each units ; 2 times for each side.</li> <li>*Frequency : 10Hz~55Hz~10Hz(1min)</li> <li>*Total amplitude : 1.5mm</li> <li>*Test times : 6hrs.(Two hrs each in three mutually perpendicular directions)</li> </ul>	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.		
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 2. Table 2		
	then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	Appearance     No damaged       DC Resistance     Within ± 30%       Change     Within ± 30%		

### **PSA** 華新科技股份有限公司 Walsin Technology Corporation

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		1
Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical specification
	3. 30±3 minutes at +85°C±3°C,	after test, meet Table 1.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
High temperature	*Temperature : 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test, meet Table 1.
	room temperature for 24±2 hrs	
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time:1000+24/-0 hrs.	after test, meet Table 1.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	% 500hrs measuring the first data then	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test, meet Table 1.
	room temperature for 24±2 hrs	

#### SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

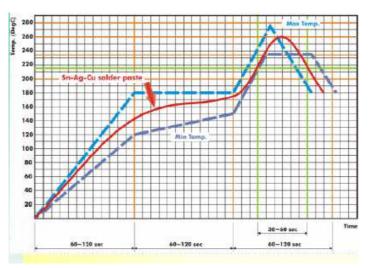


Fig 2. Infrared soldering profile

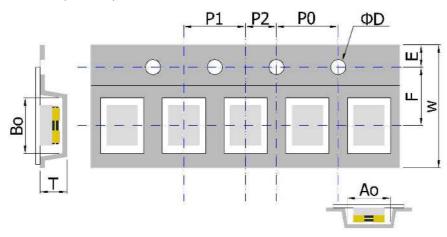
#### **ORDERING CODE**

RG	ТСМ	0806	900	Н	0	Т
Walsin	Product code	Dimension	СМ	Application	Specification	Packing
RG device	TCM :	code	Impedance	Н:	Code from 0~9	T : Reeled
	Thin Film	0806 =	900 : 90 ohm	HDMI/DVI/LVDS	dependent on	
	Common	Length 08		/SATA/PCI-/D-	different electrical	
	Mode Filter	Width 06,		Port	specification	

Minimum Ordering Quantity: 10000 pcs per reel.

#### PACKAGING

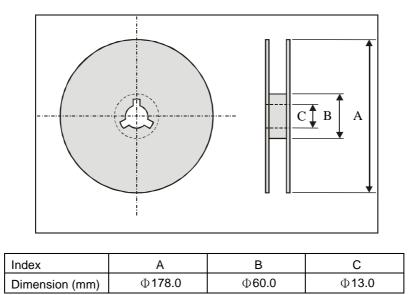
Paper Tape specifications (unit :mm)



Index	A <sub>0</sub>	B <sub>0</sub>	ΦD	Т	W
Dimension(mm)	0.78±0.03	1.04±0.03	1.55±0.05	0.6±0.03	8.0±0.10
Index	E	F	Po	P <sub>1</sub>	P <sub>2</sub>
Dimension(mm)	1.75±0.05	3.5±0.05	4.0±0.10	4.0±0.10	2.0±0.05

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#### **Reel dimensions**



Taping Quantity:10000 pieces per 7" reel

#### CAUTION OF HANDLING

#### Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

#### Storage condition

Products should be storage in the warehouse on the following conditions.

- Temperature : -10 to +40°C
- Humidity : 30 to 70% relative humidity
- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.